



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01374	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01374		
PLOT NAME = Top Assembly Drawing	GENERATED : 3/27/2018	9:58:09 PM	TEXAS INSTRUMENTS

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01374	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01374		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/27/2018	9:58:10 PM	TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
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